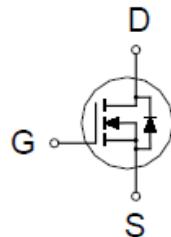
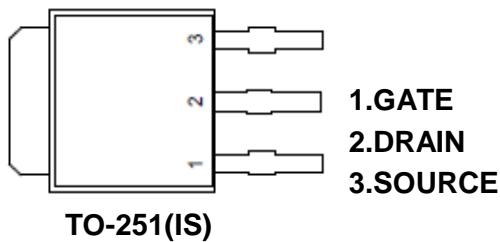


PI506BZ

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	6mΩ @ $V_{GS} = 10V$	68A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ²	I_D	68	A
		43	
Pulsed Drain Current ¹	I_{DM}	150	
Avalanche Current	I_{AS}	30.4	
Avalanche Energy	E_{AS}	46	mJ
Power Dissipation	P_D	50	W
		20	
Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	2.5	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.

²Package limitation current is 40A.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.7	3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$		5.2	9	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		4.2	6	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 20\text{A}$		80		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		1800		pF
Output Capacitance	C_{oss}			270		
Reverse Transfer Capacitance	C_{rss}			226		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		0.9		Ω
Total Gate Charge ²	$Q_g(V_{\text{GS}} = 10\text{V})$	$V_{\text{DS}} = 15\text{V}, I_D = 20\text{A}$		43.3		nC
	$Q_g(V_{\text{GS}} = 4.5\text{V})$			22.9		
Gate-Source Charge ²	Q_{gs}			6.2		
Gate-Drain Charge ²	Q_{gd}			11.3		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 15\text{V}, I_D \approx 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		25		nS
Rise Time ²	t_r			24		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			99		
Fall Time ²	t_f			57		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				68	A
Forward Voltage ¹	V_{SD}	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		21		nS
Reverse Recovery Charge	Q_{rr}			12		nC

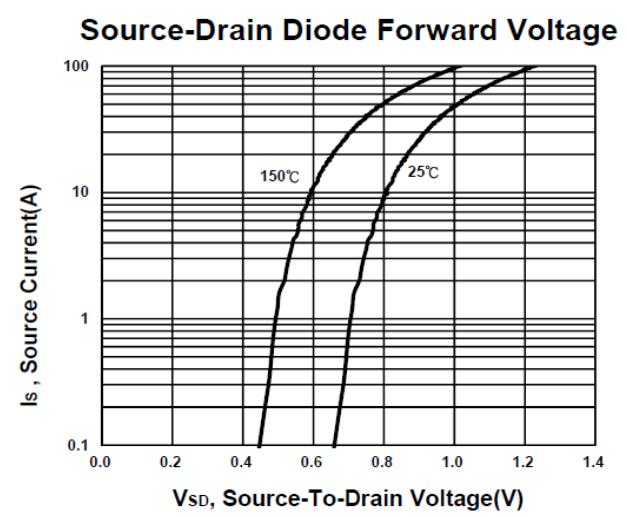
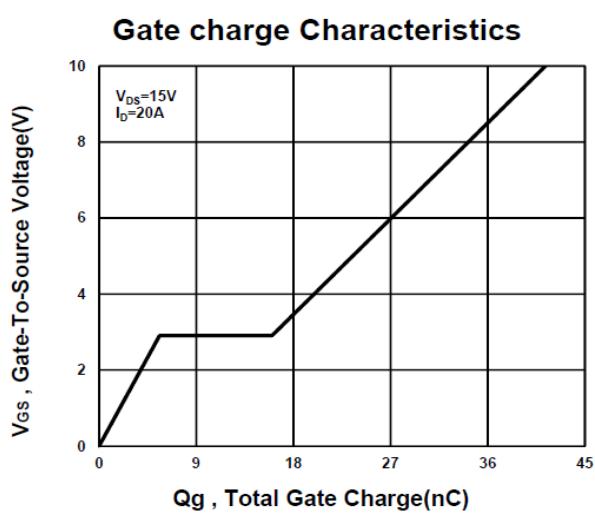
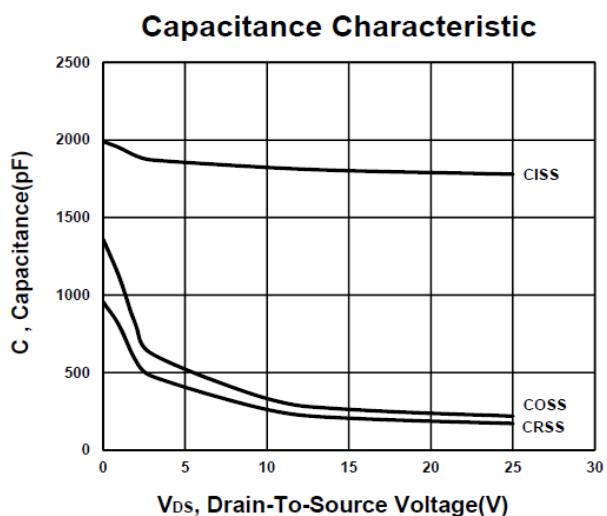
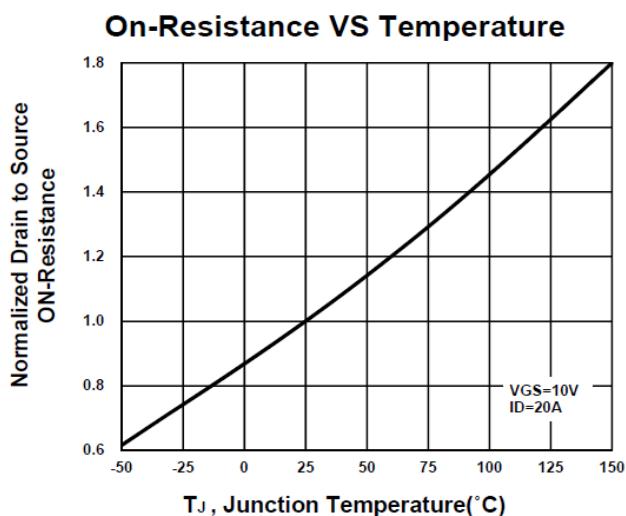
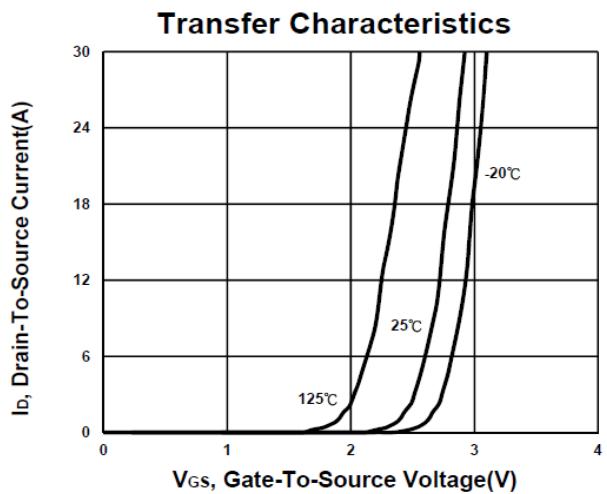
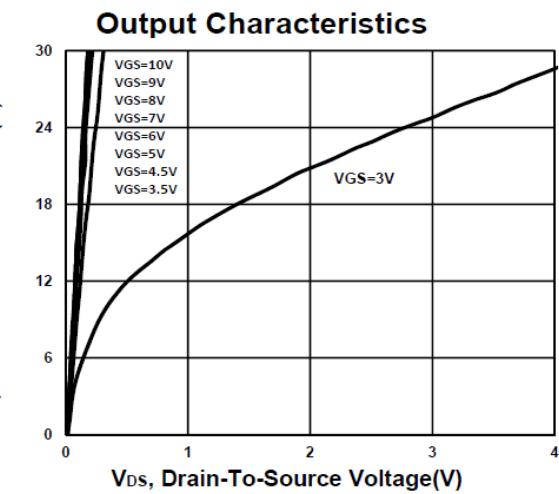
¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Package limitation current is 40A.

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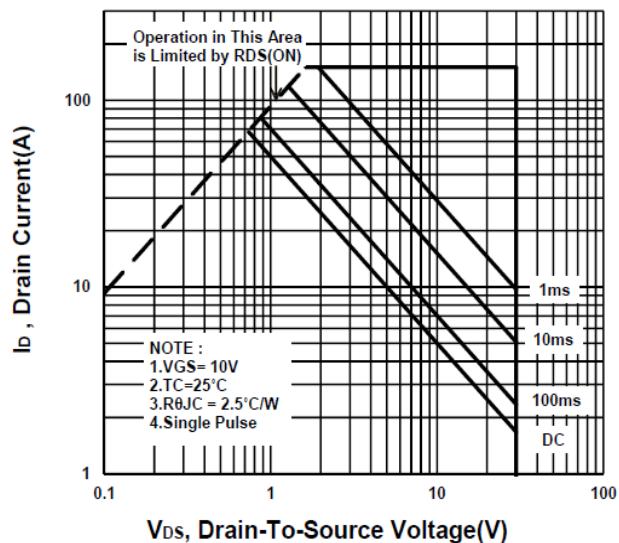
N-Channel Enhancement Mode MOSFET



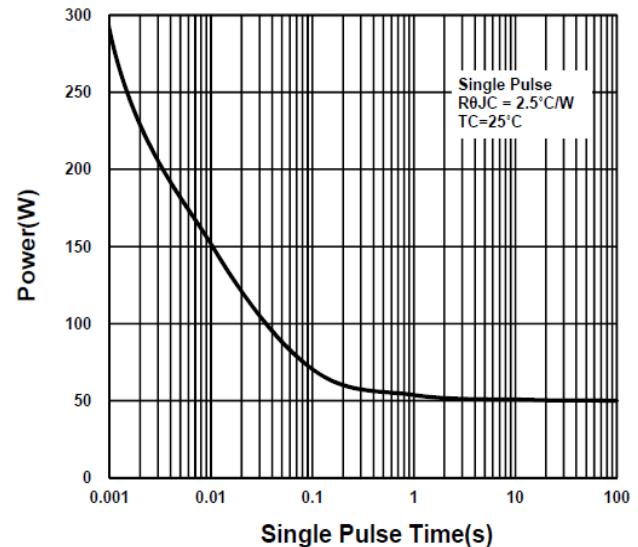
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N-Channel Enhancement Mode MOSFET

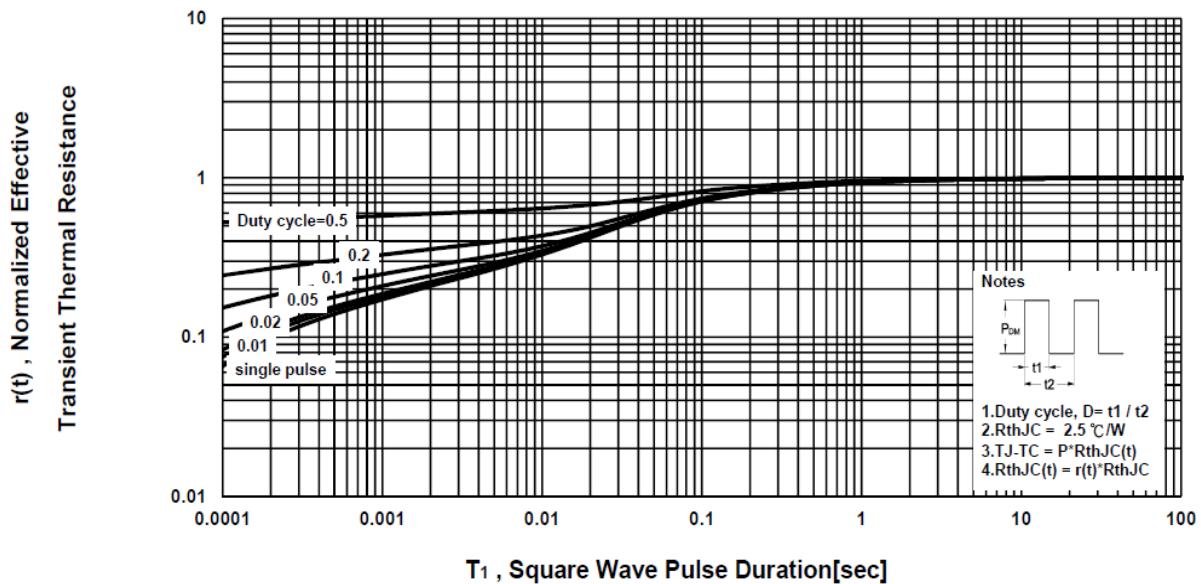
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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Package Dimension

TO-251 (IS) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	6.3	6.6	6.8	H	2.1	2.3	2.5
B	4.8	5.3	5.5	J	0.4	0.5	0.6
C	6.7		7.57	K	0.35	0.5	0.65
D	3	3.5	4.5	L	0.9		1.5
E		2.3		M	5.3		6.22
F	0.6	0.9	1.1	N	1.4	1.6	2.1
G	0.4		0.89				

